AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-8 (canceled).

Claim 9 (new): A multilayer substrate including a built-in chip-type electronic component comprising:

a laminate including a plurality of laminated dielectric layers in a lamination direction;

a chip-type electronic component disposed in the laminate and having a terminal electrode; and

a via conductor disposed in the dielectric layers in the lamination direction; wherein

the terminal electrode of the chip-type electronic component is connected to at least one of upper and lower end surfaces of the via conductor, and a connection step is provided in the via conductor.

Claim 10 (new): The multilayer substrate including the built-in chip-type electronic component according to Claim 9, wherein the dielectric layers are ceramic layers, the laminate is a ceramic laminate including a plurality of the ceramic layers, and the chip-type electronic component includes a ceramic sintered body defining an element body.

Claim 11 (new): The multilayer substrate including the built-in chip-type electronic component according to Claim 10, wherein the ceramic layers are composed of a low-temperature co-fired ceramic material, and the via conductor is composed of a conductor material including silver or copper as a main component.

Claim 12 (new): A method for manufacturing a multilayer substrate including a built-in chip-type electronic component comprising the steps of:

disposing a chip-type electronic component having a terminal electrode on a dielectric layer having a via conductor such that the terminal electrode is connected to the via conductor; and

laminating the dielectric layer having the chip-type electronic component disposed thereon and another dielectric layer to form a laminate having the built-in chip-type electronic component.

Claim 13 (new): The method for manufacturing the multilayer substrate including the built-in chip-type electronic component according to Claim 12, wherein each of the dielectric layers includes a ceramic green body, the chip-type electronic component includes a ceramic sintered body used as an element body, and the ceramic green body having the chip-type electronic component disposed thereon and the other ceramic green body are laminated to form a ceramic green laminate having the built-in chip-type electronic component, followed by firing of the ceramic green laminate.

Claim 14 (new): The method for manufacturing the multilayer substrate including the built-in chip-type electronic component according to Claim 13, wherein the other ceramic green body has a via conductor to be connected to the terminal electrode of the chip-type electronic component.

Claim 15 (new): The method for manufacturing the multilayer substrate with the built-in chip-type electronic component according to Claim 13, further comprising the steps of:

forming the ceramic green bodies using a low-temperature co-fired ceramic material; and

forming a conductor pattern composed of silver or copper as a main component in the ceramic green laminate.

Claim 16 (new): The method for manufacturing the multilayer substrate including the built-in chip-type electronic component according to Claim 13, further comprising the step of adding a shrinkage suppression layer composed of a powder, which is not substantially sintered at the sintering temperature of the ceramic green bodies, in the ceramic green laminate or on a surface thereof.